



Solder Materials

CORED WIRE

Product Name	Description	Key Attributes	Approximate Flux Content (% by Weight)	Diameter Range (mm)	Pb-Free Alloy	SnPb Alloy	IPC J-STE-004B Classification
Halogen-Free, No-Clean							
LOCTITE C 400	Cored solder wire	• Clear residue • Increased flux content for improved wetting on challenging surfaces • Award-winning multiple flux core technology that ensures consistent distribution of flux throughout the solder wire • Suitable for manual and robotic soldering	2.2	0.38 – 1.63	• 90iSC • 99C • SAC305 • SAC387	• Sn60 • Sn62 • Sn63	ROLO
Halide-Free, No-Clean							
LOCTITE C 502	Cored solder wire	• Clear residue • Good wetting on difficult substrates • Medium activity flux	2.7	0.25 – 1.63	• 99C • SAC305 • SAC387	• Sn60 • Sn62 • Sn63	ROM1
LOCTITE C 511	Cored solder wire	• Amber residue • Good wetting on difficult substrates • Heat stable • Medium activity flux	2.7	0.38 – 1.63	• 99C • SAC305 • SAC387	• Sn60 • Sn62 • Sn63	ROM1
Halide-Containing, Water Wash							
LOCTITE HYDX	Cored solder wire	• High activity flux • Excellent wetting on difficult substrates	2.0	0.38 – 1.63	• 99C • SAC305 • SAC387	• Sn60 • Sn62 • Sn63	ORH1

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LIQUID FLUX

Product Name	Description	Key Attributes	Solid Content (% by Weight)	Acid Value (mg KOH/g)	Application	IPC J-STE-004B Classification
Halide-Containing, Water Wash						
LOCTITE HYDX-20	Liquid Flux	- Highly water soluble - Residues designed to be cleaned with deionized water - Solders onto copper, brass, nickel and mild steel efficiently - Compatible with Pb-free and SnPb wave solder processes	20	24	Spray/Foam	ORH1
Halide-Free, No-Clean						
LOCTITE MF 210	Liquid flux	- Resin-free flux designed to solder onto surfaces known to have poor solderability - Recommended for applications where high throughput is required - Compatible with Pb-free and SnPb wave solder processes	2.9	22.5	Spray/Foam	ORM0
LOCTITE MF R301	Liquid flux	- Higher solids flux for better wetting on surfaces known to have reduced solderability - Minimizes bridging on complex geometries - Fully Pb-free and dual wave compatible - Solvent-based flux may be thinned with isopropyl alcohol (IPA) - Compatible with Pb-free and SnPb wave solder processes	6.0	40	Spray/Foam	ROM0
Halogen-Free, VOC-Free, No-Clean						
LOCTITE MF 300	Liquid flux	- General-purpose, resin-free, water-based flux with special formulation designed to minimize solder balling - Compatible with Pb-free and SnPb wave solder processes	4.6	37	Spray/Foam	ORM0
Halogen-Free, No-Clean						
LOCTITE MF 390HR	Liquid flux	- Exceptional through-hole fill - Recommended for automotive applications and general electrical soldering applications - Compatible with Pb-free and SnPb wave solder processes	6.0	20 – 25	Spray/Foam	ROLO

SOLDER PASTE

Product Name	Description	Key Attributes	Alloy	Particle Size Distribution	IPC J-STE-004B Classification	Optimal Shelf Life	Reflow Atmosphere
Temperature Stable, Halogen-Free, No-Clean							
LOCTITE GC 10	Pb-free, solder paste	- RoHS-compliant - Excellent resistance to high humidity - Industry leader in paste transfer efficiency - Improved stability at different storage and operating temperatures - Extended stencil life up to 72 hr. - Extended abandon time up to 24 hr. - Suitable for high-density, small to large boards	SAC305	- Type 3 - Type 4 - Type 4.5 (4A) - Type 5	ROLO	1 year at 26.5° C	Designed for air; suitable with nitrogen
Halogen-Free, No-Clean							
LOCTITE HF 212	Pb-free, solder paste	- High tack - Low voiding - RoHS-compliant - Excellent fine pitch coalescence - Designed for medium to large boards	90iSC - SAC0307 - SAC305 - SAC387	- Type 3 - Type 4 - Type 4.5 (4A) - Type 5	ROLO	6 months at 0° C – 10° C	Air and nitrogen

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